

## ABSTRACT

5 A package substrate 310 incorporating a substrate provided  
with a conductor layer 5, a conductive connecting pin 100 arranged  
to establish the electrical connection with a mother board and  
secured to the surface of the substrate, wherein a pad 16 for  
securing the conductive connecting pin is provided for the  
package substrate 310. The pad 16 is covered with an organic  
resin insulating layer 15 having an opening 18 through which  
10 the pad 16 is partially exposed to the outside. The conductive  
connecting pin 100 is secured to the pad exposed to the outside  
through the opening with a conductive adhesive agent 17 so that  
solution of the conductive connecting pin 100 from the substrate  
occurring, for example when mounting is performed is prevented.